E·XFL



Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	30/20MHz
Connectivity	UART/USART
Peripherals	POR, WDT
Number of I/O	32
Program Memory Size	32KB (32K x 8)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-QFP
Supplier Device Package	44-VQFP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts87c58x2-lie

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

	PIN NUMBER			TYPE	
MNEMONIC	DIL	LCC	VQFP 1.4	TTPE	Name And Function
MNEMONIC		PIN NU	MBER	TYPE	NAME AND FUNCTION
ALE/PROG	30	33	27	O (I)	Address Latch Enable/Program Pulse: Output pulse for latching the low byte of the address during an access to external memory. In normal operation, ALE is emitted at a constant rate of 1/6 (1/3 in X2 mode) the oscillator frequency, and can be used for external timing or clocking. Note that one ALE pulse is skipped during each access to external data memory. This pin is also the program pulse input (PROG) during EPROM programming. ALE can be disabled by setting SFR's AUXR.0 bit. With this bit set, ALE will be inactive during internal fetches.
PSEN	29	32	26	0	Program Store ENable: The read strobe to external program memory. When executing code from the external program memory, PSEN is activated twice each machine cycle, except that two PSEN activations are skipped during each access to external data memory. PSEN is not activated during fetches from internal program memory.
ĒĀ/V _{PP}	31	35	29	I	External Access Enable/Programming Supply Voltage: \overline{EA} must be externally held low to enable the device to fetch code from external program memory locations 0000H and 3FFFH (54X2) or 7FFFH (58X2). If EA is held high, the device executes from internal program memory unless the program counter contains an address greater than 3FFFH (54X2) or 7FFFH (58X2). This pin also receives the 12.75V programming supply voltage (V _{PP}) during EPROM programming. If security level 1 is programmed, \overline{EA} will be internally latched on Reset.
XTAL1	19	21	15	I	Crystal 1: Input to the inverting oscillator amplifier and input to the internal clock generator circuits.
XTAL2	18	20	14	0	Crystal 2: Output from the inverting oscillator amplifier

Table 5-1.Pin Description for 40/44 pin packages





6. TS80C54/58X2 Enhanced Features

In comparison to the original 80C52, the TS80C54/58X2 implements some new features, which are:

- The X2 option.
- The Dual Data Pointer.
- The Watchdog.
- The 4 level interrupt priority system.
- The power-off flag.
- The ONCE mode.
- The ALE disabling.
- Some enhanced features are also located in the UART and the timer 2.

6.1 X2 Feature

The TS80C54/58X2 core needs only 6 clock periods per machine cycle. This feature called "X2" provides the following advantages:

- Divide frequency crystals by 2 (cheaper crystals) while keeping same CPU power.
- Save power consumption while keeping same CPU power (oscillator power saving).
- Save power consumption by dividing dynamically operating frequency by 2 in operating and idle modes.
- Increase CPU power by 2 while keeping same crystal frequency.

In order to keep the original C51 compatibility, a divider by 2 is inserted between the XTAL1 signal and the main clock input of the core (phase generator). This divider may be disabled by software.

6.1.1 Description

The clock for the whole circuit and peripheral is first divided by two before being used by the CPU core and peripherals. This allows any cyclic ratio to be accepted on XTAL1 input. In X2 mode, as this divider is bypassed, the signals on XTAL1 must have a cyclic ratio between 40 to 60%. Figure 6-2. shows the clock generation block diagram. X2 bit is validated on XTAL1÷2 rising edge to avoid glitches when switching from X2 to STD mode. Figure 6-2. shows the mode switching waveforms.

Figure 6-1. Clock Generation Diagram



8 AT/TS8xC54/8X2



Table 7-1.AUXR1: Auxiliary Register 1

7	6	5	4	3	2	1	0
-	-	-	-	GF3	0	-	DPS

Bit Number	Bit Mnemonic	Description
7	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
6	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
5	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
4	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
3	GF3	This bit is a general purpose user flag
2	0	Reserved Always stuck at 0.
1	-	Reserved The value read from this bit is indeterminate. Do not set this bit.
0	DPS	Data Pointer Selection Clear to select DPTR0. Set to select DPTR1.

Reset Value = XXXX 00X0 Not bit addressable

User software should not write 1s to reserved bits. These bits may be used in future 8051 family products to invoke new feature. In that case, the reset value of the new bit will be 0, and its active value will be 1. The value read from a reserved bit is indeterminate.

7.1 Application

Software can take advantage of the additional data pointers to both increase speed and reduce code size, for example, block operations (copy, compare, search ...) are well served by using one data pointer as a 'source' pointer and the other one as a "destination" pointer.

ASSEMBLY LANGUAGE

; Block move using ; Destroys DPTR0 ; note: DPS exits o	g dual data), DPTR1, A opposite of	pointers A and PSW entry state	
; unless an extra l	NC AUXR1	is added	
;			
00A2	AUXR	1 EQU 0A2H	
;			
0000 909000	MOV	DPTR,#SOURCE	; address of SOURCE
0003 05A2	INC	AUXR1	; switch data pointers
0005 90A000	MOV	DPTR,#DEST	; address of DEST
0008	LOOP		
0008 05A2	INC	AUXR1	; switch data pointers
000A E0	MOVX	A, @DPTR	; get a byte from SOURCE
000B A3	INC	DPTR	; increment SOURCE address
000C 05A2	INC	AUXR1	; switch data pointers
000E F0	MOVX	@DPTR,A	; write the byte to DEST
000F A3	INC	DPTR	; increment DEST address
0010 70F6	JNZ	LOOP	; check for 0 terminator
0012 05A2	INC	AUXR1	; (optional) restore DPS

INC is a short (2 bytes) and fast (12 clocks) way to manipulate the DPS bit in the AUXR1 SFR. However, note that the INC instruction does not directly force the DPS bit to a particular state, but simply toggles it. In simple routines, such as the block move example, only the fact that DPS is toggled in the proper sequence matters, not its actual value. In other words, the block move routine works the same whether DPS is '0' or '1' on entry. Observe that without the last instruction (INC AUXR1), the routine will exit with DPS in the opposite state.





8. Timer 2

The timer 2 in the TS80C54/58X2 is compatible with the timer 2 in the 80C52.

It is a 16-bit timer/counter: the count is maintained by two eight-bit timer registers, TH2 and TL2, connected in cascade. It is controlled by T2CON register (See Table 8-1) and T2MOD register (See Table 8-2). Timer 2 operation is similar to Timer 0 and Timer 1. C/T2 selects $F_{OSC}/12$ (timer operation) or external pin T2 (counter operation) as the timer clock input. Setting TR2 allows TL2 to be incremented by the selected input.

Timer 2 has 3 operating modes: capture, autoreload and Baud Rate Generator. These modes are selected by the combination of RCLK, TCLK and CP/RL2 (T2CON), as described in the Atmel Wireless & Microcontrollers 8-bit Microcontroller Hardware description.

Refer to the Atmel Wireless & Microcontrollers 8-bit Microcontroller Hardware description for the description of Capture and Baud Rate Generator Modes.

In TS80C54/58X2 Timer 2 includes the following enhancements:

- Auto-reload mode with up or down counter
- Programmable clock-output

8.1 Auto-Reload Mode

The auto-reload mode configures timer 2 as a 16-bit timer or event counter with automatic reload. If DCEN bit in T2MOD is cleared, timer 2 behaves as in 80C52 (refer to the Atmel Wireless & Microcontrollers 8-bit Microcontroller Hardware description). If DCEN bit is set, timer 2 acts as an Up/down timer/counter as shown in Figure 8-1. In this mode the T2EX pin controls the direction of count.

When T2EX is high, timer 2 counts up. Timer overflow occurs at FFFFh which sets the TF2 flag and generates an interrupt request. The overflow also causes the 16-bit value in RCAP2H and RCAP2L registers to be loaded into the timer registers TH2 and TL2.

When T2EX is low, timer 2 counts down. Timer underflow occurs when the count in the timer registers TH2 and TL2 equals the value stored in RCAP2H and RCAP2L registers. The underflow sets TF2 flag and reloads FFFFh into the timer registers.

The EXF2 bit toggles when timer 2 overflows or underflows according to the the direction of the count. EXF2 does not generate any interrupt. This bit can be used to provide 17-bit resolution





8.1.1 Programmable Clock-Output

In the clock-out mode, timer 2 operates as a 50%-duty-cycle, programmable clock generator (See Figure 8-2) . The input clock increments TL2 at frequency $F_{OSC}/2$. The timer repeatedly counts to overflow from a loaded value. At overflow, the contents of RCAP2H and RCAP2L registers are loaded into TH2 and TL2. In this mode, timer 2 overflows do not generate interrupts. The formula gives the clock-out frequency as a function of the system oscillator frequency and the value in the RCAP2H and RCAP2L registers :

$$Clock - OutFrequency = \frac{F_{osc}}{4 \times (65536 - RCAP2H/RCAP2L)}$$

For a 16 MHz system clock, timer 2 has a programmable frequency range of 61 Hz $(F_{OSC}/2^{16})$ to 4 MHz $(F_{OSC}/4)$. The generated clock signal is brought out to T2 pin (P1.0).

Timer 2 is programmed for the clock-out mode as follows:

- Set T2OE bit in T2MOD register.
- Clear C/T2 bit in T2CON register.
- Determine the 16-bit reload value from the formula and enter it in RCAP2H/RCAP2L registers.





Table 8-2.	T2MOD Register	

T2MOD	- Timer 2	2 Mode	Control	Register	(C9h)
-------	-----------	--------	---------	----------	-------

7	6	5	4	3	2	1	0		
-	-	-	-	-	-	T2OE	DCEN		
Bit Number	Bit Mnemonic		Description						
7	-	Reserved The value read	Reserved The value read from this bit is indeterminate. Do not set this bit.						
6	-	Reserved The value read	eserved he value read from this bit is indeterminate. Do not set this bit.						
5	-	Reserved The value read	Reserved The value read from this bit is indeterminate. Do not set this bit.						
4	-	Reserved The value read	Reserved The value read from this bit is indeterminate. Do not set this bit.						
3	-	Reserved The value read	Reserved The value read from this bit is indeterminate. Do not set this bit.						
2	-	Reserved The value read	Reserved The value read from this bit is indeterminate. Do not set this bit.						
1	T2OE	Timer 2 Output Clear to progra Set to program	Timer 2 Output Enable bit Clear to program P1.0/T2 as clock input or I/O port. Set to program P1.0/T2 as clock output.						
0	DCEN	Down Counter Enable bit Clear to disable timer 2 as up/down counter. Set to enable timer 2 as up/down counter.							

Reset Value = XXXX XX00b Not bit addressable The following is an example of how to use given addresses to address different slaves:

Slave A:	SADDR <u>SADEN</u> Given	1111 0001b <u>1111 1010b</u> 1111 0X0Xb
Slave B:	SADDR <u>SADEN</u> Given	1111 0011b <u>1111 1001b</u> 1111 0XX1b
Slave C:	SADDR <u>SADEN</u> Given	1111 0010b <u>1111 1101b</u> 1111 00X1b

The SADEN byte is selected so that each slave may be addressed separately.

For slave A, bit 0 (the LSB) is a don't-care bit; for slaves B and C, bit 0 is a 1. To communicate with slave A only, the master must send an address where bit 0 is clear (e.g. 1111 0000b). For slave A, bit 1 is a 1; for slaves B and C, bit 1 is a don't care bit. To communicate with slaves B and C, but not slave A, the master must send an address with bits 0 and 1 both set (e.g. 1111

0011b).

To communicate with slaves A, B and C, the master must send an address with bit 0 set, bit 1 clear, and bit 2 clear (e.g. 1111 0001b).

9.1.3 Broadcast Address

A broadcast address is formed from the logical OR of the SADDR and SADEN registers with zeros defined as don't-care bits, e.g.:

SADDR	0101 0110b	
SADEN	1111 1100b	
Broadcast =SADDR OR SADEN	1111 111Xb	

The use of don't-care bits provides flexibility in defining the broadcast address, however in most applications, a broadcast address is FFh. The following is an example of using broadcast addresses:

Slave A:	SADDR <u>SADEN</u> Broadcast	1111 0001b <u>1111 1010b</u> 1111 1X11b,
Slave B:	SADDR <u>SADEN</u> Broadcast	1111 0011b <u>1111 1001b</u> 1111 1X11B,
Slave C:	SADDR= <u>SADEN</u> Broadcast	1111 0010b <u>1111 1101b</u> 1111 1111b

For slaves A and B, bit 2 is a don't care bit; for slave C, bit 2 is set. To communicate with all of the slaves, the master must send an address FFh. To communicate with slaves A and B, but not slave C, the master can send and address FBh.

9.1.4 Reset Addresses

On reset, the SADDR and SADEN registers are initialized to 00h, i.e. the given and broadcast addresses are XXXX XXXb (all don't-care bits). This ensures that the serial port will reply to any address, and so, that it is backwards compatible with the 80C51 microcontrollers that do not support automatic address recognition.



11. Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirely : the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occured during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

11.1 Power-Down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 9-4., PCON register).

In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V_{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts INT0 and INT1 are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.

Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 11-1. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.

Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C54/58X2 into power-down mode.



17. TS87C54/58X2 EPROM

17.1 EPROM Structure

The TS87C54/58X2 EPROM is divided in two different arrays:

- the code array:16/32 Kbytes.
- the encryption array:64 bytes.
- In addition a third non programmable array is implemented:
- the signature array: 4 bytes.

17.2 EPROM Lock System

The program Lock system, when programmed, protects the on-chip program against software piracy.

17.2.1 Encryption Array

Within the EPROM array are 64 bytes of encryption array that are initially unprogrammed (all FF's). Every time a byte is addressed during program verify, 6 address lines are used to select a byte of the encryption array. This byte is then exclusive-NOR'ed (XNOR) with the code byte, creating an encrypted verify byte. The algorithm, with the encryption array in the unprogrammed state, will return the code in its original, unmodified form.

When using the encryption array, one important factor needs to be considered. If a byte has the value FFh, verifying the byte will produce the encryption byte value. If a large block (>64 bytes) of code is left unprogrammed, a verification routine will display the content of the encryption array. For this reason all the unused code bytes should be programmed with random values. This will ensure program protection.

17.2.2 Program Lock Bits

The three lock bits, when programmed according to Table 17-1., will provide different level of protection for the on-chip code and data.

Program Lock Bits				
Security level	LB1	LB2	LB3	Protection Description
1	U	U	U	No program lock features enabled. Code verify will still be encrypted by the encryption array if programmed. MOVC instruction executed from external program memory returns non encrypted data.
2	Р	U	U	MOVC instruction executed from external program memory are disabled from fetching code bytes from internal memory, \overline{EA} is sampled and latched on reset, and further programming of the EPROM is disabled.
3	U	Р	U	Same as 2, also verify is disabled.
4	U	U	Р	Same as 3, also external execution is disabled.

Table 17-1.Program Lock bits

U: unprogrammed,

P: programmed

WARNING: Security level 2 and 3 should only be programmed after EPROM and Core verification.





19. Electrical Characteristics

19.1 Absolute Maximum Ratings ⁽¹⁾

Ambiant Temperature Under Bias: C = commercial0°C to 70°C I = industrial -40°C to 85°C Storage Temperature-65°C to + 150°C Voltage on V_{CC} to V_{SS}-0.5 V to + 7 V Voltage on V_{PP} to V_{SS}-0.5 V to + 13 V Voltage on Any Pin to V_{SS}-0.5 V to V_{CC} + 0.5 V Power Dissipation1 W⁽²⁾

- 1. Stresses at or above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
- 2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

19.2 Power consumption measurement

Since the introduction of the first C51 devices, every manufacturer made operating lcc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel presents a new way to measure the operating lcc:

Using an internal test ROM, the following code is executed:

Label:

SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

19.3 DC Parameters for Standard Voltage

 $\begin{array}{l} T_{A}=0^{\circ}C \ to \ +70^{\circ}C; \ V_{SS}=0 \ V; \ V_{CC}=5 \ V \pm 10\%; \ F=0 \ to \ 40 \ MHz. \\ T_{A}=-40^{\circ}C \ to \ +85^{\circ}C; \ V_{SS}=0 \ V; \ V_{CC}=5 \ V \pm 10\%; \ F=0 \ to \ 40 \ MHz. \end{array}$

Table 19-1.	DC Parameters in Standard Voltage
-------------	-----------------------------------

Symbol	Parameter	Min	Тур	Max	Unit	Test Conditions
V _{IL}	Input Low Voltage	-0.5		0.2 V _{CC} - 0.1	V	
V _{IH}	Input High Voltage except XTAL1, RST	0.2 V _{CC} + 0.9		V _{CC} + 0.5	V	
V _{IH1}	Input High Voltage, XTAL1, RST	0.7 V _{CC}		V _{CC} + 0.5	V	
				0.3	V	$I_{OL} = 100 \ \mu A^{(4)}$
V _{OL}	Output Low Voltage, ports 1, 2, 3 ⁽⁶⁾			0.45	V	I _{OL} = 1.6 mA ⁽⁴⁾
				1.0	V	I _{OL} = 3.5 mA ⁽⁴⁾

- 5. Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.
- Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows: Maximum I_{OL} per port pin: 10 mA Maximum I_{OL} per 8-bit port: Port 0: 26 mA Ports 1, 2 and 3: 15 mA Maximum total I_{OL} for all output pins: 71 mA If I_{OL} exceeds the test condition, V_{OL} may exceed the related specification. Pins are not guaranteed to sink current greater than the listed test conditions.
- 7. For other values, please contact your sales office.
- Operating I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 19-5.), V_{IL} = V_{SS} + 0.5 V,

 $V_{IH} = V_{CC} - 0.5V$; XTAL2 N.C.; $\overline{EA} = Port 0 = V_{CC}$; RST = V_{SS} . The internal ROM runs the code 80 FE (label: SJMP label). I_{CC} would be slightly higher if a crystal oscillator is used. Measurements are made with OTP products when possible, which is the worst case.





All other pins are disconnected.





All other pins are disconnected.





Figure 19-3. I_{CC} Test Condition, Idle Mode



All other pins are disconnected.











19.5.2 External Program Memory Characteristics

Table 19-5. Symbol Description

Symbol	Parameter
т	Oscillator clock period
T _{LHLL}	ALE pulse width
T _{AVLL}	Address Valid to ALE
T _{LLAX}	Address Hold After ALE
T _{LLIV}	ALE to Valid Instruction In
T _{LLPL}	ALE to PSEN
T _{PLPH}	PSEN Pulse Width
T _{PLIV}	PSEN to Valid Instruction In
T _{PXIX}	Input Instruction Hold After PSEN
T _{PXIZ}	Input Instruction FloatAfter PSEN
T _{PXAV}	PSEN to Address Valid
T _{AVIV}	Address to Valid Instruction In
T _{PLAZ}	PSEN Low to Address Float

 Table 19-6.
 AC Parameters for Fix Clock

Speed	- 40 I	M MHz	- X2 n 30 60 MH;	V node MHz z equiv.	۔ standard M	V mode 40 Hz	- X2 n 20 I 40 MH;	L node MHz z equiv.	- standar 30 I	L d mode MHz	Units
Symbol	Min	Max	Min	Max	Min	Max	Min	Max	Min	Max	
Т	25		33		25		50		33		ns
T _{LHLL}	40		25		42		35		52		ns
T _{AVLL}	10		4		12		5		13		ns
T _{LLAX}	10		4		12		5		13		ns
T _{LLIV}		70		45		78		65		98	ns
T _{LLPL}	15		9		17		10		18		ns
T _{PLPH}	55		35		60		50		75		ns
T _{PLIV}		35		25		50		30		55	ns
T _{PXIX}	0		0		0		0		0		ns
T _{PXIZ}		18		12		20		10		18	ns
T _{AVIV}		85		53		95		80		122	ns
T _{PLAZ}		10		10		10		10		10	ns

Symbol	Туре	Standard Clock	X2 Clock	-М	-V	-L	Units
T _{RLRH}	Min	6 T - x	3 T - x	20	15	25	ns
T _{WLWH}	Min	6 T - x	3 T - x	20	15	25	ns
T _{RLDV}	Max	5 T - x	2.5 T - x	25	23	30	ns
T _{RHDX}	Min	x	х	0	0	0	ns
T _{RHDZ}	Max	2 T - x	T - x	20	15	25	ns
T _{LLDV}	Max	8 T - x	4T -x	40	35	45	ns
T _{AVDV}	Max	9 T - x	4.5 T - x	60	50	65	ns
T _{LLWL}	Min	3 T - x	1.5 T - x	25	20	30	ns
T _{LLWL}	Max	3 T + x	1.5 T + x	25	20	30	ns
T _{AVWL}	Min	4 T - x	2 T - x	25	20	30	ns
T _{QVWX}	Min	T - x	0.5 T - x	15	10	20	ns
T _{QVWH}	Min	7 T - x	3.5 T - x	15	10	20	ns
T _{WHQX}	Min	T - x	0.5 T - x	10	8	15	ns
T _{RLAZ}	Max	х	х	0	0	0	ns
T _{WHLH}	Min	T - x	0.5 T - x	15	10	20	ns
T _{WHLH}	Max	T + x	0.5 T + x	15	10	20	ns

Table 19-10. AC Parameters for a Variable Clock: derating formula

19.5.5 External Data Memory Write Cycle







Symbol	Туре	Standard Clock	X2 Clock	-М	-V	-L	Units
T _{XLXL}	Min	12 T	6 T				ns
T _{QVHX}	Min	10 T - x	5 T - x	50	50	50	ns
T _{XHQX}	Min	2 T - x	T - x	20	20	20	ns
T _{XHDX}	Min	х	х	0	0	0	ns
T _{XHDV}	Max	10 T - x	5 T- x	133	133	133	ns

Table 19-13. AC Parameters for a Variable Clock: derating formula

19.5.8 Shift Register Timing Waveforms

Figure 19-9. Shift Register Timing Waveforms









This diagram indicates when signals are clocked internally. The time it takes the signals to propagate to the pins, however, ranges from 25 to 125 ns. This propagation delay is dependent on variables such as temperature and pin loading. Propagation also varies from output to output and component. Typically though ($T_A=25^{\circ}C$ fully loaded) RD and WR propagation delays are approximately 50ns. The other signals are typically 85 ns. Propagation delays are incorporated in the AC specifications.





20. Ordering Information

Table 20-1.	
-------------	--

Possible Ordering Entries

Part Number	Supply Voltage	Temperature Range	Package	Packing
TS80C54X2xxx-MCA	-5 to +/-10%	Commercial	PDIL40	Stick
TS80C54X2xxx-MCB	-5 to +/-10%	Commercial	PLCC44	Stick
TS80C54X2xxx-MCC	-5 to +/-10%	Commercial	PQFP44	Tray
TS80C54X2xxx-MCE	-5 to +/-10%	Commercial	VQFP44	Tray
TS80C54X2xxx-VCA	-5 to +/-10%	Commercial	PDIL40	Stick
TS80C54X2xxx-VCB	-5 to +/-10%	Commercial	PLCC44	Stick
TS80C54X2xxx-VCC	-5 to +/-10%	Commercial	PQFP44	Tray
TS80C54X2xxx-VCE	-5 to +/-10%	Commercial	VQFP44	Tray
TS80C54X2xxx-LCA	-5 to +/-10%	Commercial	PDIL40	Stick
TS80C54X2xxx-LCB	-5 to +/-10%	Commercial	PLCC44	Stick
TS80C54X2xxx-LCC	-5 to +/-10%	Commercial	PQFP44	Tray
TS80C54X2xxx-LCE	-5 to +/-10%	Commercial	VQFP44	Tray
TS80C54X2xxx-MIA	-5 to +/-10%	Industrial	PDIL40	Stick
TS80C54X2xxx-MIB	-5 to +/-10%	Industrial	PLCC44	Stick
TS80C54X2xxx-MIC	-5 to +/-10%	Industrial	PQFP44	Tray
TS80C54X2xxx-MIE	-5 to +/-10%	Industrial	VQFP44	Tray
TS80C54X2xxx-VIA	-5 to +/-10%	Industrial	PDIL40	Stick
TS80C54X2xxx-VIB	-5 to +/-10%	Industrial	PLCC44	Stick
TS80C54X2xxx-VIC	-5 to +/-10%	Industrial	PQFP44	Tray
TS80C54X2xxx-VIE	-5 to +/-10%	Industrial	VQFP44	Tray
TS80C54X2xxx-LIA	-5 to +/-10%	Industrial	PDIL40	Stick
TS80C54X2xxx-LIB	-5 to +/-10%	Industrial	PLCC44	Stick
TS80C54X2xxx-LIC	-5 to +/-10%	Industrial	PQFP44	Tray
TS80C54X2xxx-LIE	-5 to +/-10%	Industrial	VQFP44	Tray
AT80C54X2zzz-3CSUM	-5 to +/-10%	Industrial & Green	PDIL40	Stick
AT80C54X2zzz-SLSUM	-5 to +/-10%	Industrial & Green	PLCC44	Stick
AT80C54X2zzz-RLTUM	-5 to +/-10%	Industrial & Green	VQFP44	Tray
AT80C54X2zzz-3CSUL	-5 to +/-10%	Industrial & Green	PDIL40	Stick
AT80C54X2zzz-SLSUL	-5 to +/-10%	Industrial & Green	PLCC44	Stick
AT80C54X2zzz-RLTUL	-5 to +/-10%	Industrial & Green	VQFP44	Tray
AT80C54X2zzz-3CSUV	-5 to +/-10%	Industrial & Green	PDIL40	Stick
AT80C54X2zzz-SLSUV	-5 to +/-10%	Industrial & Green	PLCC44	Stick
AT80C54X2zzz-RLTUV	-5 to +/-10%	Industrial & Green	VQFP44	Tray
TS87C54X2-MCA	5V ±10%	Commercial	PDIL40	Stick
TS87C54X2-MCB	5V ±10%	Commercial	PLCC44	Stick

8 AT/TS8xC54/8X2



Part Number	Supply Voltage	Temperature Range	Package	Packing
TS80C58X2xxx-MCA	-5 to +/-10%	Commercial	PDIL40	Stick
TS80C58X2xxx-MCB	-5 to +/-10%	Commercial	PLCC44	Stick
TS80C58X2xxx-MCC	-5 to +/-10%	Commercial	PQFP44	Tray
TS80C58X2xxx-MCE	-5 to +/-10%	Commercial	VQFP44	Tray
TS80C58X2xxx-VCA	-5 to +/-10%	Commercial	PDIL40	Stick
TS80C58X2xxx-VCB	-5 to +/-10%	Commercial	PLCC44	Stick
TS80C58X2xxx-VCC	-5 to +/-10%	Commercial	PQFP44	Tray
TS80C58X2xxx-VCE	-5 to +/-10%	Commercial	VQFP44	Tray
TS80C58X2xxx-LCA	-5 to +/-10%	Commercial	PDIL40	Stick
TS80C58X2xxx-LCB	-5 to +/-10%	Commercial	PLCC44	Stick
TS80C58X2xxx-LCC	-5 to +/-10%	Commercial	PQFP44	Tray
TS80C58X2xxx-LCE	-5 to +/-10%	Commercial	VQFP44	Tray
TS80C58X2xxx-MIA	-5 to +/-10%	Industrial	PDIL40	Stick
TS80C58X2xxx-MIB	-5 to +/-10%	Industrial	PLCC44	Stick
TS80C58X2xxx-MIC	-5 to +/-10%	Industrial	PQFP44	Tray
TS80C58X2xxx-MIE	-5 to +/-10%	Industrial	VQFP44	Tray
TS80C58X2xxx-VIA	-5 to +/-10%	Industrial	PDIL40	Stick
TS80C58X2xxx-VIB	-5 to +/-10%	Industrial	PLCC44	Stick
TS80C58X2xxx-VIC	-5 to +/-10%	Industrial	PQFP44	Tray
TS80C58X2xxx-VIE	-5 to +/-10%	Industrial	VQFP44	Tray
TS80C58X2xxx-LIA	-5 to +/-10%	Industrial	PDIL40	Stick
TS80C58X2xxx-LIB	-5 to +/-10%	Industrial	PLCC44	Stick
TS80C58X2xxx-LIC	-5 to +/-10%	Industrial	PQFP44	Tray
TS80C58X2xxx-LIE	-5 to +/-10%	Industrial	VQFP44	Tray
	·			
AT80C58X2zzz-3CSUM	-5 to +/-10%	Industrial & Green	PDIL40	Stick
AT80C58X2zzz-SLSUM	-5 to +/-10%	Industrial & Green	PLCC44	Stick
AT80C58X2zzz-RLTUM	-5 to +/-10%	Industrial & Green	VQFP44	Tray
AT80C58X2zzz-3CSUL	-5 to +/-10%	Industrial & Green	PDIL40	Stick
AT80C58X2zzz-SLSUL	-5 to +/-10%	Industrial & Green	PLCC44	Stick
AT80C58X2zzz-RLTUL	-5 to +/-10%	Industrial & Green	VQFP44	Tray
AT80C58X2zzz-3CSUV	-5 to +/-10%	Industrial & Green	PDIL40	Stick
AT80C58X2zzz-SLSUV	-5 to +/-10%	Industrial & Green	PLCC44	Stick
AT80C58X2zzz-RLTUV	-5 to +/-10%	Industrial & Green	VQFP44	Tray
TS87C58X2-MCA	5V ±10%	Commercial	PDIL40	Stick
TS87C58X2-MCB	5V ±10%	Commercial	PLCC44	Stick
TS87C58X2-MCC	5V ±10%	Commercial	PQFP44	Tray



Atmel Corporation

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 487-2600

Regional Headquarters

Europe

Atmel Sarl Route des Arsenaux 41 Case Postale 80 CH-1705 Fribourg Switzerland Tel: (41) 26-426-5555 Fax: (41) 26-426-5500

Asia

Room 1219 Chinachem Golden Plaza 77 Mody Road Tsimshatsui East Kowloon Hong Kong Tel: (852) 2721-9778 Fax: (852) 2722-1369

Japan

9F, Tonetsu Shinkawa Bldg. 1-24-8 Shinkawa Chuo-ku, Tokyo 104-0033 Japan Tel: (81) 3-3523-3551 Fax: (81) 3-3523-7581

Atmel Operations

Memory

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 436-4314

Microcontrollers

2325 Orchard Parkway San Jose, CA 95131, USA Tel: 1(408) 441-0311 Fax: 1(408) 436-4314

La Chantrerie BP 70602 44306 Nantes Cedex 3, France Tel: (33) 2-40-18-18-18 Fax: (33) 2-40-18-19-60

ASIC/ASSP/Smart Cards

Zone Industrielle 13106 Rousset Cedex, France Tel: (33) 4-42-53-60-00 Fax: (33) 4-42-53-60-01

1150 East Cheyenne Mtn. Blvd. Colorado Springs, CO 80906, USA Tel: 1(719) 576-3300 Fax: 1(719) 540-1759

Scottish Enterprise Technology Park Maxwell Building East Kilbride G75 0QR, Scotland Tel: (44) 1355-803-000 Fax: (44) 1355-242-743

RF/Automotive

Theresienstrasse 2 Postfach 3535 74025 Heilbronn, Germany Tel: (49) 71-31-67-0 Fax: (49) 71-31-67-2340

1150 East Cheyenne Mtn. Blvd. Colorado Springs, CO 80906, USA Tel: 1(719) 576-3300 Fax: 1(719) 540-1759

Biometrics/Imaging/Hi-Rel MPU/ High Speed Converters/RF Datacom

Avenue de Rochepleine BP 123 38521 Saint-Egreve Cedex, France Tel: (33) 4-76-58-30-00 Fax: (33) 4-76-58-34-80

Literature Requests www.atmel.com/literature

Disclaimer: The information in this document is provided in connection with Atmel products. No license, express or implied, by estoppel or otherwise, to any intellectual property right is granted by this document or in connection with the sale of Atmel products. EXCEPT AS SET FORTH IN ATMEL'S TERMS AND CONDI-TIONS OF SALE LOCATED ON ATMEL'S WEB SITE, ATMEL ASSUMES NO LIABILITY WHATSOEVER AND DISCLAIMS ANY EXPRESS, IMPLIED OR STATUTORY WARRANTY RELATING TO ITS PRODUCTS INCLUDING, BUT NOT LIMITED TO, THE IMPLIED WARRANTY OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, OR NON-INFRINGEMENT. IN NO EVENT SHALL ATMEL BE LIABLE FOR ANY DIRECT, INDIRECT, CONSEQUENTIAL, PUNTIVE, SPECIAL OR INCIDEN-TAL DAMAGES (INCLUDING, WITHOUT LIMITATION, DAMAGES FOR LOSS OF PROFITS, BUSINESS INTERRUPTION, OR LOSS OF INFORMATION) ARISING OUT OF THE USE OR INABILITY TO USE THIS DOCUMENT, EVEN IF ATMEL HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES. Atmel makes no representations or warranties with respect to the accuracy or completeness of the contents of this document and reserves the right to make changes to specifications and product descriptions at any time without notice. Atmel does not make any commitment to update the information contained herein. Unless specifically providedotherwise, Atmel products are not suitable for, and shall not be used in, automotive applications. Atmel'sAtmel's products are not intended, authorized, or warranted for use as components in applications intended to support or sustain life.

© Atmel Corporation 2006. All rights reserved. Atmel[®], logo and combinations thereof, and Everywhere You Are[®] are the trademarks or registered trademark of Atmel Corporation or its subsidiaries. Other terms and product names may be trademarks of others.

